ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

<table>
<thead>
<tr>
<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: PMP10632</th>
<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
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<tr>
<td>PLOT NAME = Top Assembly Drawing</td>
<td>GENERATED : 3/9/2017 2:08:59 PM</td>
<td>TSiX AS ASRI NTS ISTRUMENTS</td>
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COMPONENTS MARKED ‘DNP’ SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

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<th>PCB VIEWED FROM BOTTOM SIDE</th>
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<td>PLOT NAME = Bottom Assembly Drawing</td>
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